



# BUK9675-100A

N-channel TrenchMOS logic level FET

18 August 2015

Product data sheet

## 1. General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

## 2. Features and benefits

- AEC Q101 compliant
- Low conduction losses due to low on-state resistance

## 3. Applications

- Automotive and general purpose power switching

## 4. Quick reference data

Table 1. Quick reference data

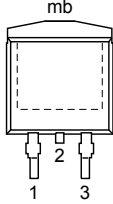
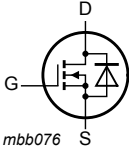
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$	-	-	100	V
$I_D$	drain current	$V_{GS} = 5\text{ V}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 2</a>	-	-	23	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C};$ <a href="#">Fig. 1</a>	-	-	98	W
<b>Static characteristics</b>						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 10\text{ A}; T_j = 25\text{ °C};$ <a href="#">Fig. 12</a>	-	55	72	mΩ
		$V_{GS} = 5\text{ V}; I_D = 10\text{ A}; T_j = 25\text{ °C};$ <a href="#">Fig. 12</a>	-	60	75	mΩ
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 23\text{ A}; V_{sup} \leq 100\text{ V}; R_{GS} = 50\text{ }\Omega;$ $V_{GS} = 5\text{ V}; T_{j(init)} = 25\text{ °C};$ unclamped; <a href="#">Fig. 4</a>	<a href="#">[1][2]</a>	-	100	mJ

[1] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.

[2] Refer to application note AN10273 for further information.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 <p>D2PAK (SOT404)</p>	
2	D	drain		
3	S	source		
mb	D	mounting base; connected to drain		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9675-100A	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

## 7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9675-100A	BUK9675-100A

## 8. Limiting values

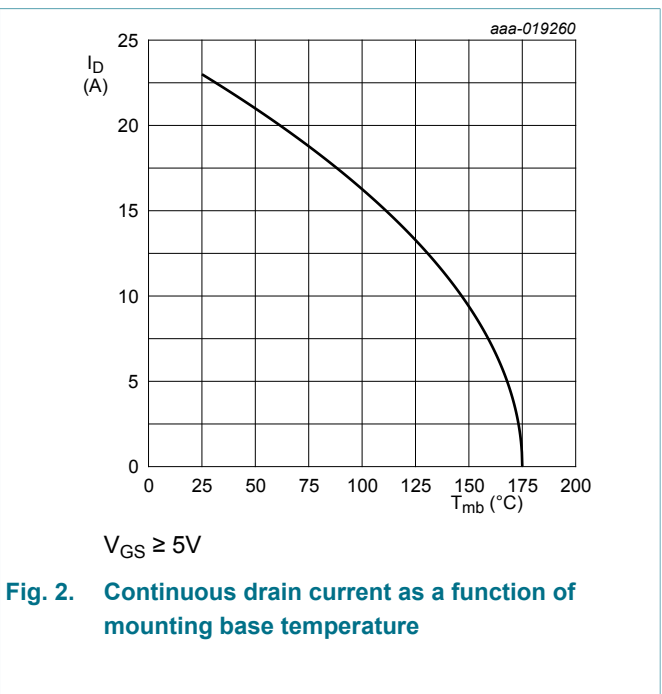
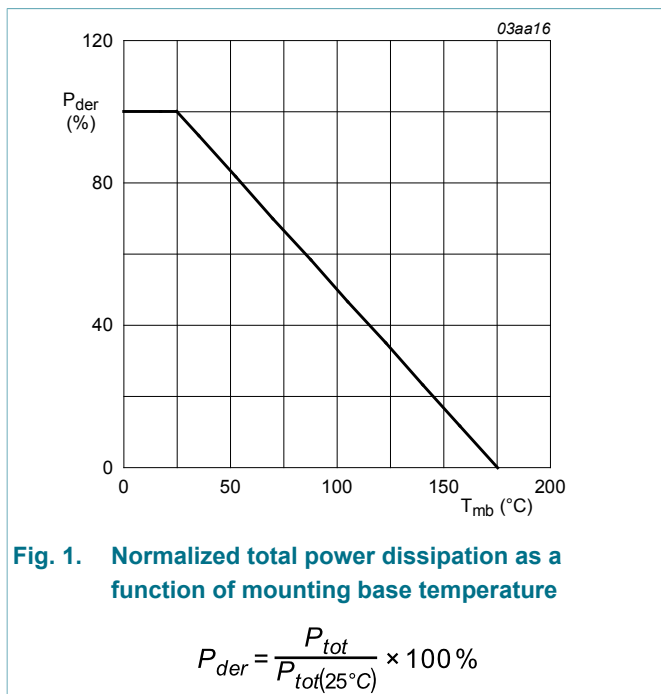
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 175\text{ °C}$	-	100	V
$V_{DGR}$	drain-gate voltage	$R_{GS} = 20\text{ k}\Omega$	-	100	V
$V_{GS}$	gate-source voltage		-15	15	V
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 1</a>	-	98	W
$I_D$	drain current	$T_{mb} = 100\text{ °C}$ ; $V_{GS} = 5\text{ V}$ ; <a href="#">Fig. 2</a>	-	16	A
		$T_{mb} = 25\text{ °C}$ ; $V_{GS} = 5\text{ V}$ ; <a href="#">Fig. 2</a>	-	23	A
$I_{DM}$	peak drain current	$T_{mb} = 25\text{ °C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; <a href="#">Fig. 3</a>	-	92	A
$T_{stg}$	storage temperature		-55	175	°C
$T_j$	junction temperature		-55	175	°C

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25\text{ °C}$	-	23	A
$I_{SM}$	peak source current	pulsed; $t_p \leq 10\ \mu\text{s}$ ; $T_{mb} = 25\text{ °C}$	-	92	A
<b>Avalanche ruggedness</b>					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 23\text{ A}$ ; $V_{sup} \leq 100\text{ V}$ ; $R_{GS} = 50\ \Omega$ ; $V_{GS} = 5\text{ V}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; unclamped; <a href="#">Fig. 4</a>	[1][2]	-	100 mJ

- [1] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
- [2] Refer to application note AN10273 for further information.



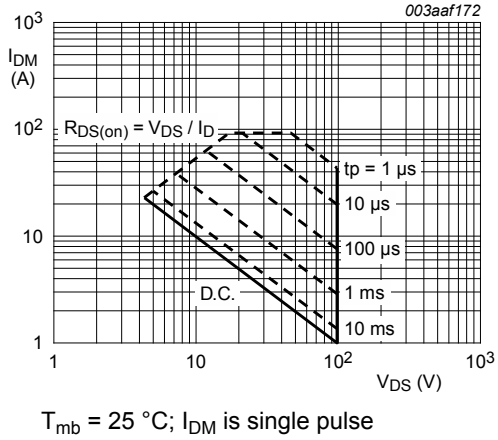


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

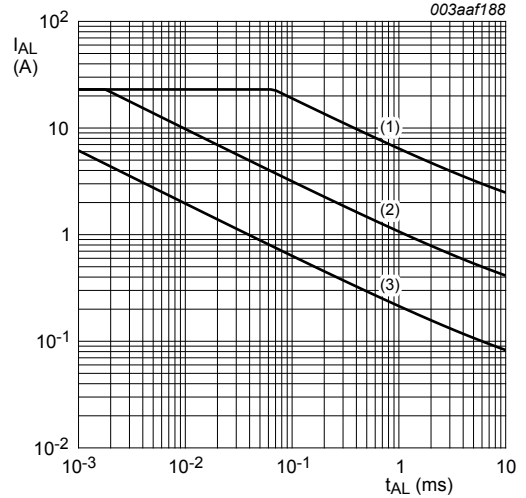


Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base		-	-	1.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Minimum footprint; FR4 board	-	50	-	K/W

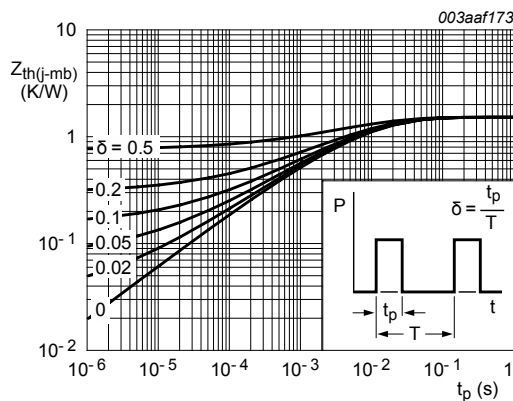


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	100	-	-	V
		$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^\circ\text{C}$	89	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^\circ\text{C};$ <a href="#">Fig. 10</a>	0.5	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C};$ <a href="#">Fig. 10</a> ; <a href="#">Fig. 11</a>	1	1.5	2	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^\circ\text{C};$ <a href="#">Fig. 10</a>	-	-	2.3	V
$I_{DSS}$	drain leakage current	$V_{DS} = 100 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175 \text{ }^\circ\text{C}$	-	-	500	$\mu\text{A}$
		$V_{DS} = 100 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	0.05	10	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 10 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2	100	nA
		$V_{GS} = -10 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ <a href="#">Fig. 12</a>	-	55	72	m $\Omega$
		$V_{GS} = 5 \text{ V}; I_D = 10 \text{ A}; T_j = 175 \text{ }^\circ\text{C};$ <a href="#">Fig. 13</a>	-	-	188	m $\Omega$
		$V_{GS} = 4.5 \text{ V}; I_D = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ <a href="#">Fig. 12</a>	-	61	84	m $\Omega$
		$V_{GS} = 5 \text{ V}; I_D = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ <a href="#">Fig. 12</a>	-	60	75	m $\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 10 \text{ A}; V_{DS} = 80 \text{ V}; V_{GS} = 5 \text{ V};$ <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>	-	24.3	-	nC
$Q_{GS}$	gate-source charge		-	3	-	nC
$Q_{GD}$	gate-drain charge		-	12.2	-	nC
$C_{iss}$	input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^\circ\text{C};$ <a href="#">Fig. 16</a>	-	1278	1704	pF
$C_{oss}$	output capacitance		-	129	155	pF
$C_{rss}$	reverse transfer capacitance		-	88	120	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 30 \text{ V}; R_L = 1.2 \text{ } \Omega; V_{GS} = 5 \text{ V};$ $R_{G(ext)} = 10 \text{ } \Omega; T_j = 25 \text{ }^\circ\text{C}$	-	13	20	ns
$t_r$	rise time		-	120	168	ns
$t_{d(off)}$	turn-off delay time		-	58	87	ns
$t_f$	fall time		-	57	86	ns
$L_D$	internal drain inductance	from drain lead 6 mm from package to centre of die; $T_j = 25 \text{ }^\circ\text{C}$	-	4.5	-	nH

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		from upper edge of drain tab to centre of die; $T_j = 25\text{ }^\circ\text{C}$	-	2.5	-	nH
$L_S$	internal source inductance	from source lead to source bond pad; $T_j = 25\text{ }^\circ\text{C}$	-	7.5	-	nH
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 10\text{ A}$ ; $V_{GS} = 0\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; Fig. 17	-	0.85	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 20\text{ A}$ ; $dI_S/dt = -100\text{ A}/\mu\text{s}$ ; $V_{GS} = 0\text{ V}$ ;	-	53.7	-	ns
$Q_r$	recovered charge	$V_{DS} = 30\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$	-	126	-	nC

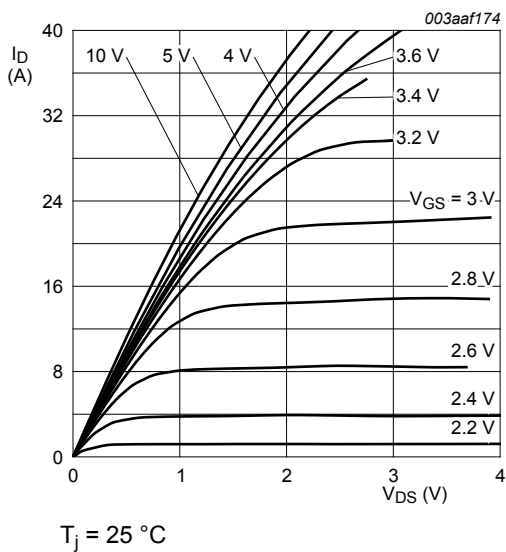


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

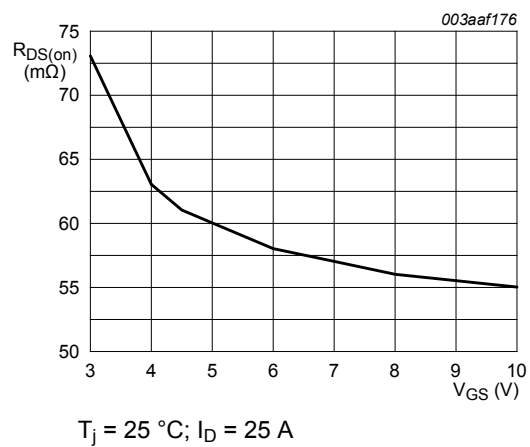


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

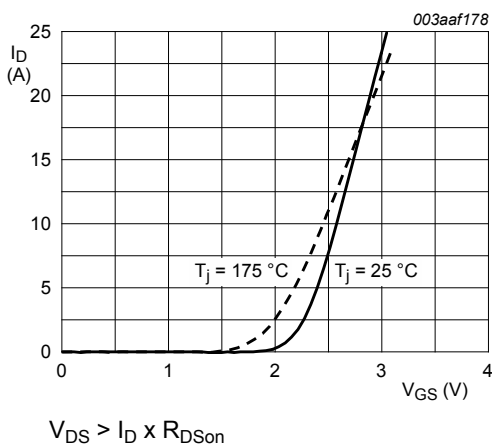


Fig. 8. Transfer characteristics: drain current as a function of gate-source voltage; typical values

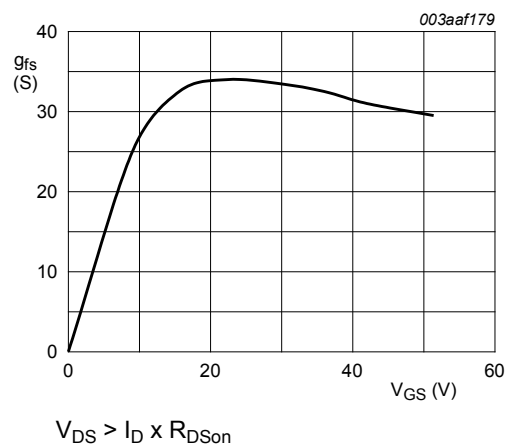
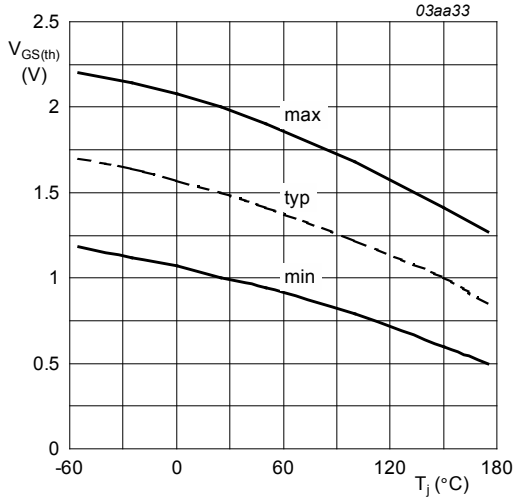
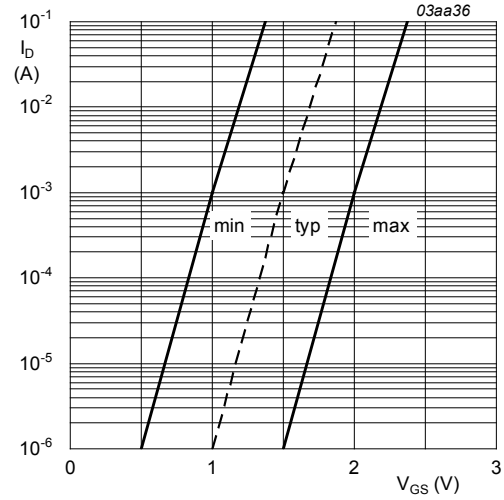


Fig. 9. Forward transconductance as a function of drain current; typical values



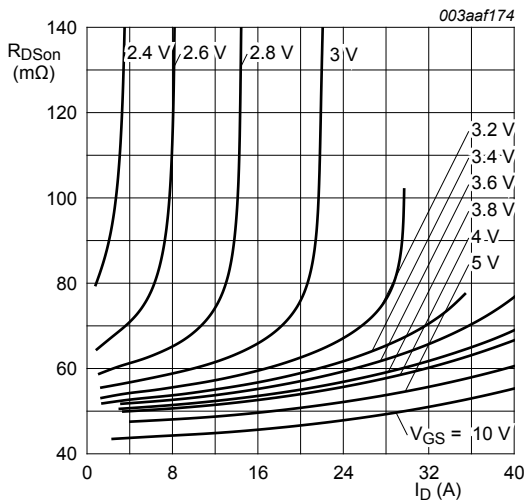
**Fig. 10. Gate-source threshold voltage as a function of junction temperature**

$$I_D = 1\text{mA}; V_{DS} = V_{GS}$$



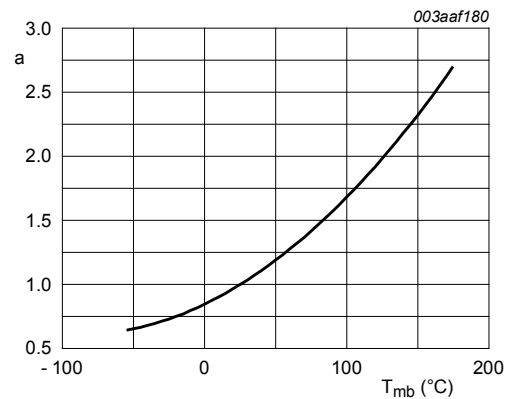
$$T_j = 25\text{ }^\circ\text{C}; V_{DS} = 5\text{ V}$$

**Fig. 11. Sub-threshold drain current as a function of gate-source voltage**



$$T_j = 25\text{ }^\circ\text{C}$$

**Fig. 12. Drain-source on-state resistance as a function of drain current; typical values**



**Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature**

$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ\text{C})}}$$

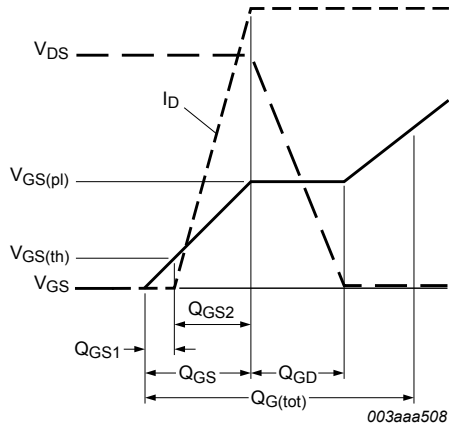
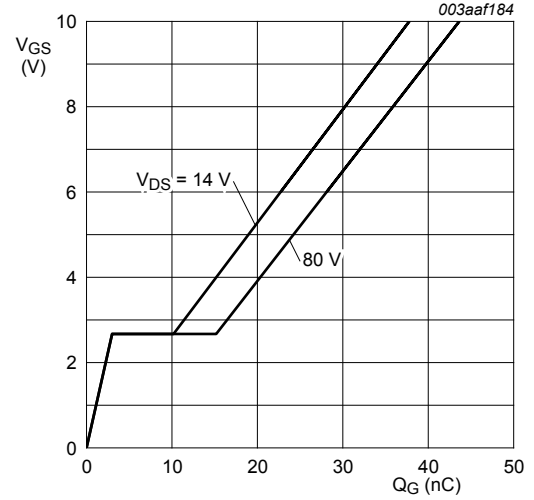
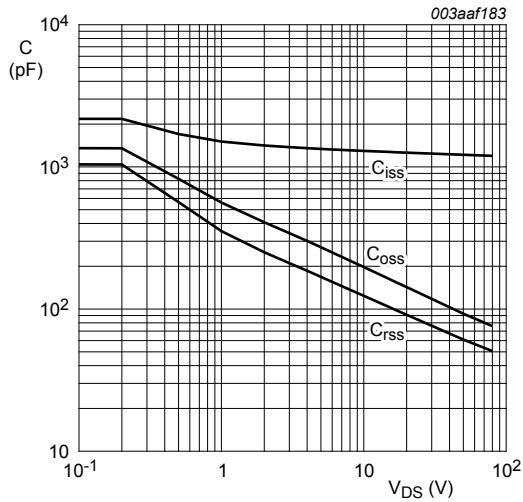


Fig. 14. Gate charge waveform definitions



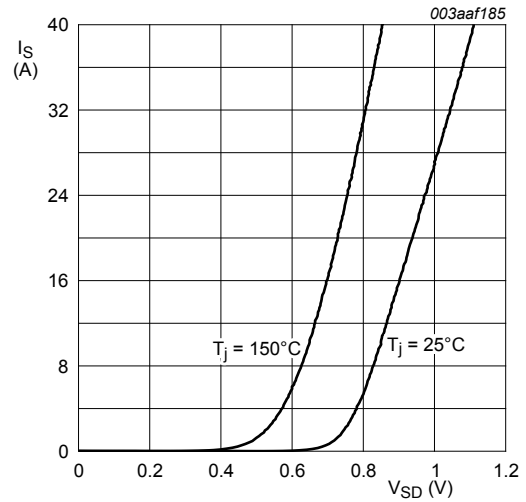
$T_j = 25\text{ }^\circ\text{C}$ ;  $I_D = 10\text{ A}$

Fig. 15. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0\text{ V}$ ;  $f = 1\text{ MHz}$

Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{GS} = 0\text{ V}$

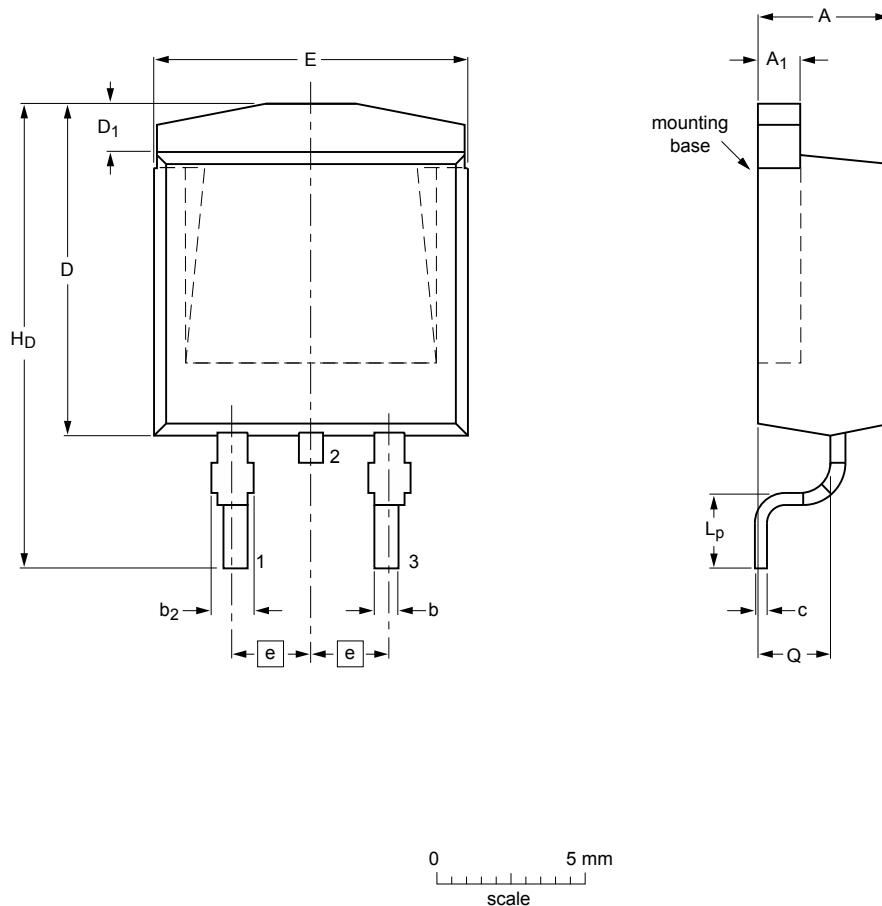
Fig. 17. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values



### 11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

SOT404



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	b <sub>2</sub>	c	D	D <sub>1</sub>	E	e	H <sub>D</sub>	L <sub>p</sub>	Q
max	4.5	1.40	0.85	1.45	0.64	11	1.6	10.3		15.8	2.9	2.6
nom									2.54			
min	4.1	1.27	0.60	1.05	0.46		1.2	9.7		14.8	2.1	2.2

sot404\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT404					-06-03-16- 13-02-25

**Fig. 18. Package outline D2PAK (SOT404)**

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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